



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Vernon M. Williams and

Attorney Docket No.: 501062.01

Filed

: Concurrently Herewith

Michael D. Gifford

Title

: LEADFRAME AND METHOD FOR REDUCING MOLD COMPOUND ADHESION

**PROBLEMS** 

## GENERAL AUTHORIZATION

Box Patent Application Commissioner of Patents Washington, D.C. 20231

Sir:

With respect to the above-identified application, the Commissioner is authorized to charge any fees under 37 C.F.R. §§ 1.16 and 1.17 which may be required and to treat any concurrent or future reply requiring a petition for an extension of time under 37 C.F.R. § 1.136(a)(3) for its timely submission as incorporating a petition therefor for the appropriate length of time and to charge any fees which may be required during the course of prosecution, or credit any overpayment, to Deposit Account No. 50-1266.

Date October 10, 2001

Edward W. Bulchis Registration No. 26,847

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